3D Packaging and Integration Japan TC Chapter

Meeting Summary and Minutes

Japan Standards Spring Meetings 2026
Monday, March 9, 2026 2:00 PM – 5:40 PM JST
SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

TC Chapter Announcements

Next TC Chapter Meeting

Monday, June 5, 2026 2:00 PM – 4:00 PM JST

SEMI Japan, Tokyo, Japan/ Official Virtual TC Chapter Meeting (Hybrid)

Table 1 Meeting Attendees

Italics indicates virtual participants.

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuriya (iNEMI), Haruo Shimamoto (AIST)
SEMI Staff: Akiko Yoshida (SEMI Japan)

Company	*Last*	*First*	*Company*	*Last*	*First*
Acteon NEXT	*Komatsu*	*Shoji*	*Self*	*Takahashi*	*Mark*
AIST	*Shimamoto*	*Haruo*	*Semilab Japan KK*	*Kitamura*	*Isaya*
AiT	Kato	Kazunori	*Semilab Semiconductor Physics Laboratory*	*Szucs*	*Tamas*
DISCO	*Gonsui*	*Shinobu*	Shin-Etsu Polymer	Odashima	Satoshi
FUJIFILM	Aoshima	Toshihide	Towa Laserfront	Hayasaka	Noboru
GENETEC	*Tsunobuchi*	*Hirokazu*	*V TECHNOLOGY*	*Yamazaki*	*Kuniaki*
iNEMI	*Tsuriya*	*Masahiro*			
Kanagawa Institute of Advanced Industria and Technology	*Nemoto*	*Shunsuke*	*SEMI-HQ*	*Lok*	*Boon Keng*
KOKUSAI ELECTRIC	*Matsuda*	*Mitsuhiro*	SEMI Japan	Hirabara	Takeaki
Yokohama National University	Inoue	Fumihiro	SEMI Japan	Koga	Nahoko
Yokohama National University	Sano	Marie	SEMI Japan	Yoshida	Akiko

Table 2 Leadership Changes

WG/TF/SC/TC Name	*Previous Leader*	*New Leader*
3D Packaging & Integration 5 Year Review TF	Masahiro Tsuriya (iNEMI)	N/A

Table 3 TC Chapter Structure Changes

Previous WG/TF/SC Name	*New WG/TF/SC Name or Status Change*
Steering Working Group	Disbanded
Wafer Bonding Pressure Evaluation TF	Wafer Surface Pressure Mapping by Pressure Measurement Film Task Force (TF name is changed)

Table 4 Ballot Results

Document #	*Document Title*	*Committee Action*
7398	New Standard: Test Method for Wafer Bond Strength Measurement by Double-Cantilever Beam	**Passed** with Editorial Changes

#1 **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

#2 **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 5 Ratification Ballot Results

Document #	*Document Title*	*ISC A&R Action*	*A&R Forms*
None			

#1 **Passed** Ratification ballots will be submitted to SEMI publication for final processing.

#2 **Failed** Ratification ballots were returned to the originating task forces for re-work and re-balloting or abandoning.

Table 6 Activities Approved by the GCS between meetings of the TC Chapter

#	*Type*	*SC/TF/WG*	*Details*
None			

Table 7 Authorized Activities

Listing of all revised or new SNARF(s) approved by the Originating TC Chapter.

#	*Type*	*SC/TF/WG*	*Details*
7460	SNARF	3D Packaging & Integration 5-Year Review TF	Line Item Revision to SEMI G82-1115, SPECIFICATION FOR 300 mm LOAD PORT FOR FRAME CASSETTES IN BACKEND PROCESS
7461	SNARF	3D Packaging & Integration 5-Year Review TF	Line Item Revision to G95-1120, SPECIFICATION FOR MECHANICAL FEATURES OF 450 mm LOAD PORT FOR TAPE FRAME CASSETTES IN THE BACKEND PROCESS
7462	SNARF	3D Packaging & Integration 5-Year Review TF	Line Item Revision to SEMI G74-0699 (Reapproved 1020), SPECIFICATION FOR TAPE FRAME FOR 300 mm WAFERS
7463	SNARF	3D Packaging & Integration 5-Year Review TF	Line Item to SEMI G87-1108 (Reapproved 1020), SPECIFICATION FOR PLASTIC TAPE FRAME FOR 300 mm WAFER
	TFOF	Wafer Surface Pressure Mapping by Pressure Measurement Film TF	Revise TFOF to change the TF name From: Wafer Bonding Pressure Evaluation Task Force To: Wafer Surface Pressure Mapping by Pressure Measurement Film Task Force
7464	SNARF	Wafer Surface Pressure Mapping by Pressure Measurement Film TF	New Standard: Guide for Using Pressure Measurement Film for Wafer Surface Pressure Mapping in Equipment Alignment Processes

#1 SNARFs and TFOFs are available for review on the SEMI Web site at:

http://downloads.semi.org/web/wstdsbal.nsf/TFOFSNARF

Table 8 Authorized Ballots

#	*When*	*TF*	*Details*
7460	Cycle 4, 2026	3D Packaging & Integration 5-Year Review TF	Line Item Revision to SEMI G82-1115, SPECIFICATION FOR 300 mm LOAD PORT FOR FRAME CASSETTES IN BACKEND PROCESS
7461	Cycle 4, 2026	3D Packaging & Integration 5-Year Review TF	Line Item Revision to G95-1120, SPECIFICATION FOR MECHANICAL FEATURES OF 450 mm LOAD PORT FOR TAPE FRAME CASSETTES IN THE BACKEND PROCESS
7462	Cycle 5, 2026	3D Packaging & Integration 5-Year Review TF	Line Item Revision to SEMI G74-0699 (Reapproved 1020), SPECIFICATION FOR TAPE FRAME FOR 300 mm WAFERS
7463	Cycle 5, 2026	3D Packaging & Integration 5-Year Review TF	G87-1108 (Reapproved 1020), SPECIFICATION FOR PLASTIC TAPE FRAME FOR 300 mm WAFER

Table 9 SNARF(s) Granted a One-Year Extension

#	*TF*	*Title*	*Expiration Date*
None			

Table 10 SNARF(s) Cancelled

#	*TF*	*Title*	*Expiration Date*
None			

Table 11 Standard(s) to receive Inactive Status

Standard Designation	*Title*
None	

Table 12 New Action Items

Item #	*Assigned to*	*Details*
3DP&I_20260309-01	SEMI Staff	To send the ballot review results of Doc.#7398 to the ISC A&R SC for procedural review.
3DP&I_20260309-02	5-year review TF (Tsuriya-san)	To Submit SEMI G82 and G95 Line Item Revision Ballot for Cycle 4, 2026.
3DP&I_20260309-03	5-year review TF (Shimamoto-san)	To submit SEMI G74 and G87 Line Item Revision Ballot for Cycle 5, 2026.

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
3DP&I_20250519-03	5-Year Review TF	To prepare Line Item/ Major Revision SNARFs for SEMI G74 and G87. →Closed
3DP&I_20250519-04	5-Year Review TF	To prepare Line Item Revision SNARFs for SEMI G82 and G95. →Closed
3DP&I_20251006-01	Wafer Bond Strength	To submit the Letter Ballot for Doc.#7398 in Cycle 1 or 2, 2026. →Closed

Table 13 Previous Meeting Action Items

Item #	*Assigned to*	*Details*
	Measurement by Double-cantilever Beam Task Force	
3DP&I_20251006-02	SEMI Staff	To send the ballot review results of Doc.#7359, 7360, 7361 to the ISC A&R SC for procedural review. →Closed
3DP&I_20251006-03	Wafer Bonding Pressure TF	To have a TF kick off meeting and reconsider the TF name. →Closed

1 Welcome, Reminders, and Introductions

Kazunori Kato (AiT) called the meeting to order at 14:00. The meeting reminders on antitrust issues, intellectual property issues, and holding meetings with international attendance were reviewed. Attendees introduced themselves.

Attachment: 01_Required_Meeting_Element Dec 2024_JPupdated

2 Review of Previous Meeting Minutes

The TC Chapter reviewed the minutes of the previous meeting.

Motion:	Approve the minutes as written.
By / 2nd:	Shoji Komatsu (Acteon NEXT)/ Satoshi Odashima (Shin-Etsu Polymer)
Discussion:	None.
Vote:	13-Y 0-N. Motion passed.

Attachment: 02_3DP&I_JA_Minutes_20251006_R0

3 Technical Committee Award

Technical Committee Award recognizes leadership in document development, committee management, task force coordination, and Standards dissemination. Fumihiro Inoue (Yokohama National University) received the award for his outstanding leadership and active contributions.

4 Ballot Review

NOTE 1: TC Chapter adjudication of ballots is detailed in the Audits & Review (A&R) Subcommittee Forms for procedural review. The A&R forms are available as attachments to these minutes. The attachment file name for each balloted document is provided.

4.1 *Doc.#7398, New Standard: Test Method for Wafer Bond Strength Measurement by Double-Cantilever Beam*

- This document passed with editorial changes. Refer to the attachment for more details.

Attachment: 03_7398_Ballot Review

5 Liaison Report

5.1 *Japan Regional Standards Committee (JRSC)*

Akiko Yoshida (SEMI Japan) reported that SEMI Japan honors outstanding SEMI Standards members, as determined by the JRSC. At SEMICON Japan 2025, awards were presented at the SEMI Standard Friendship Party & Awards Ceremony to individuals who made significant contributions to the SEMI Standards Program. The recipients included:

- SEMI Japan International Collaboration Award: Hirokazu Tunobuchi (GENETIC) and Haruna Hayashi (Tokyo Electron)
- SEMI Japan Honor Award: Tetsuya Nakai (SUMCO)
- SEMI Japan Special Award: Masanori Yoshise (Self)

Attachment: 04_JRSC Rport_March 2026_R0

5.2 *Global Coordinating Subcommittee (GCS)*

Akiko Yoshida (SEMI Japan) reported for the GCS that there was no GCS discussion or voting between 3D Packaging and Integration Japan TC Chapter meetings.

5.3 *3D Packaging and Integration North America TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the 3D Packaging and Integration North America TC Chapter. Of note.

- Last meeting was held on February 12, 2026 during NA Winter Meetings and next meeting will be held on May 14 in conjunction with ASMC in Albany, New York.
- John Ciraldo (WD Advanced Material) newly became a TC co-chair.
- Doc.#7331, New Standard: Guide for Peel Testing of RDLs and Other Traces Used Within Advanced Packages and Structures passed TC Chapter review as balloted.

Attachment: 05_NA 3DP&I Liaison Report Feb2026 v1

Staff Note: The liaison report file was not sent to the Japan TC Chapter on the day of the TC Chapter meeting, but it was obtained afterwards and attached to the meeting minutes.

5.4 *3D Packaging and Integration Taiwan TC Chapter*

Akiko Yoshida (SEMI Japan) reported for the 3D Packaging and Integration Taiwan TC Chapter that there had been no updates from the previous meeting.

6 SEMI Staff Report

Akiko Yoshida (SEMI Japan) gave the SEMI Staff Report. Of notes:

- In 2025, 14 new SEMI Standards were released, including D88, M95, and T27, which were developed by Japan TC Chapters.
- The SEMI HQ IT Team has rebuilt SVM to guarantee login access for all members in China. Following internal testing, the beta version was launched in February. Updates have been made to improve performance based on user feedback. All enhancements are expected to be completed shortly.

Attachment: 06_Staff_HQ Report Feb 2026 _JA_R2

7 Subcommittee and Task Force Reports

7.1 *3DS IC Bonded Layer Inspection Metrology Task Force*

Haruo Shimamoto (AIST) reported for the 3DS IC Bonded Layer Inspection Metrology TF. The draft Doc.#7299, New Standard: Guide for 3DIS IC Bonded Layer Inspection Metrology is nearly completed with minor revisions expected. The TF will present the final draft at the next TC Chapter meeting.

7.2 *Wafer Bond Strength Measurement by Double-cantilever Beam Task Force*

Fumihiro Inoue (Yokohama National University) reported for the Wafer Bond Strength Measurement by Double-cantilever Beam TF. Doc.#7398, New Standard: Test Method for Wafer Bond Strength Measurement by Double-Cantilever Beam was submitted for Cycle 1, 2026 and the ballot passed TC Chapter review with editorial changes (refer to 4.1 above). The TF will address received comments as new business.

7.3 *3D Packaging & Integration 5-Year Review Task Force*

Masahiro Tsuriya (iNEMI) reported for the 3D Packaging and Integration 5-year Review TF stating that all documents scheduled for review were examined and actions were determined. He proposed the following SNARFs and ballot authorization.

Motion:	Approve the SNARF for Line Item Revision to SEMI G82-1115 (Reapproved 1220), SPECIFICATION FOR 300 mm LOAD PORT FOR FRAME CASSETTES IN BACKEND PROCESS
By / 2nd:	Masahiro Tsuriya (iNEMI)/ Shoji Komatsu (Acteon NEXT)
Discussion:	None.
Vote:	9-Y 0-N. Motion passed.

Motion:	Authorize the above document for Letter Ballot in Cycle 4, 2026.
By / 2nd:	Masahiro Tsuriya (iNEMI)/ Shoji Komatsu (Acteon NEXT)
Discussion:	None.
Vote:	10-Y 0-N. Motion passed.

Motion:	Approve the SNARF for Line Item Revision to SEMI SEMI G95-1120, SPECIFICATION FOR MECHANICAL FEATURES OF 450 mm LOAD PORT FOR TAPE FRAME CASSETTES IN THE BACKEND PROCESS
By / 2nd:	Masahiro Tsuriya (iNEMI)/ Shoji Komatsu (Acteon NEXT)
Discussion:	None.
Vote:	10-Y 0-N. Motion passed.

Motion:	Authorize the above document for Letter Ballot in Cycle 4, 2026.
By / 2nd:	Masahiro Tsuriya (iNEMI)/ Shoji Komatsu (Acteon NEXT)
Discussion:	None.
Vote:	10-Y 0-N. Motion passed.

Subsequently, Haruo Shimamoto (AIST) presented the proposed SNARFs and ballot authorization. Regarding the revision of SEMI G74, a member of the PIC NA TC Chapter reached out to the TF to request updates to G74. However, due to limited resources, the TF decided to implement only minimal modifications to the document at this point. He indicated that further changes would be addressed by them as appropriate.

Motion:	Approve the SNARF for Line Item Revision of SEMI G74-0699 (Reapproved 1020), SPECIFICATION FOR TAPE FRAME FOR 300 mm WAFERS
By / 2nd:	Haruo Shimamoto (AIST)/ Shoji Komatsu (Acteon NEXT)
Discussion:	None.
Vote:	11-Y 0-N. Motion passed.

Motion:	Authorize the above document for Letter Ballot in Cycle 5, 2026.
By / 2nd:	Haruo Shimamoto (AIST)/ Shoji Komatsu (Acteon NEXT)
Discussion:	None.
Vote:	11-Y 0-N. Motion passed.

Motion: Approve the SNARF for Line Item Revision to G87-1108 (Reapproved 1020), SPECIFICATION FOR PLASTIC TAPE FRAME FOR 300 mm WAFER
By / 2nd: Haruo Shimamoto (AIST)/ Shoji Komatsu (Acteon NEXT)
Discussion: None.
Vote: 11-Y 0-N. Motion passed.

Motion: Authorize the above document for Letter Ballot in Cycle 5, 2026.
By / 2nd: Haruo Shimamoto (AIST)/ Shoji Komatsu (Acteon NEXT)
Discussion: None.
Vote: 11-Y 0-N. Motion passed.

Attachment: 07_SNARF_G82-2603_R1
08_SNARF_G95-2603_R1
09_SNARF_G074-00-0699-1020R
10_SNARF_G087-00-1108-1020R

After receiving the necessary approvals, Masahiro Tsuriya (iNEMI), longtime document maintenance lead, announced his resignation as TF co-leader.

7.4 *3D Packaging & Integration Steering Group*

Masahiro Tsuriya (iNEMI) announced that the 3D Packaging & Integration Steering Group will be dissolved as they completed their mission.

Motion: Disband the 3D Packaging & Integration Steering Group
By / 2nd: Masahiro Tsuriya (iNEMI)/ Haruo Shimamoto (AIST)
Discussion: None.
Vote: 9-Y 0-N. Motion passed.

7.5 *Wafer Bonding Pressure Task Force*

Toshihide Aoshima (FUJIFILM) reported for the Wafer Bonding Pressure TF. Since forming in October 2025, the TF has met monthly to review the SNARF's Scope, discuss a suitable TF name, and begin drafting their document. Then, he proposed the change in the TF name and presented the SNARF after a two-week review by the global 3D Packaging and Integration TC members.

Motion: Revise TFOF to change the TF name from Wafer Bonding Pressure TF to Wafer Surface Pressure Mapping by Pressure Measurement Film TF
By / 2nd: Toshihide Aoshima (FUJIFILM)/ Shoji Komatsu (Acteon NEXT)
Discussion: None.
Vote: 10-Y 0-N. Motion passed.

Motion: Approve the SNARF for New Standard: Guide for Using Pressure Measurement Film for Wafer Surface Pressure Mapping in Equipment Alignment Processes
By / 2nd: Toshihide Aoshima (FUJIFILM)/ Shoji Komatsu (Acteon NEXT)
Discussion: None.
Vote: 10-Y 0-N. Motion passed.

Attachment: 11_20260309_SEMI STD Meeting Materials in EN v2_Toshihide Aoshima
12_TFOF_Sept2024_Toshihide Aoshima（FUJIFILM）v2
13_20260217_SNARF_Toshihide Aoshima（FUJIFILM）v5

8 Old Business

8.1 *Project Period Review*

No SNARF will be expiring soon.

8.2 *5-year Review*

Please refer to 7.3 and 9.1 for details.

9 New Business

9.1 *SEMI 3D23 Revision Activity*

Shoji Komatsu (Acteon NEXT) suggested initiating revision activities of SEMI 3D23-0721, Specification for Glass Carrier Characteristics for Panel Level Packaging (PLP) Applications, which is under 5-year review. SEMI 3D23 was developed under the 3D Packaging and Integration TC, to specify the basic physical dimensions for the glass carrier intended to be used for panel level package processing, in alignment with SEMI T24, which was developed by the Traceability TC to specify a marking symbology that can be used to mark glass carrier characteristics for panel level packaging. He intends to include 310 mm^2 panel, as part of the SATAS project, in the Scope of SEMI 3D23. He would propose establishing a new TF at the next TC Chapter meeting to address this revision.

Attachment: 14_310 Standardization of 2D Codes on Panels

10 Action Item Review

10.1 *Open Action Items*

Item #	*Assigned to*	*Details*
3DP&I_20250519-03	5-Year Review TF	To prepare Line Item/ Major Revision SNARFs for SEMI G74 and G87. →Closed
3DP&I_20250519-04	5-Year Review TF	To prepare Line Item Revision SNARFs for SEMI G82 and G95. →Closed
3DP&I_20251006-01	Wafer Bond Strength Measurement by Double-cantilever Beam Task Force	To submit the Letter Ballot for Doc.#7398 in Cycle 1 or 2, 2026. →Closed
3DP&I_20251006-02	SEMI Staff	To send the ballot review results of Doc.#7359, 7360, 7361 to the ISC A&R SC for procedural review. →Closed
3DP&I_20251006-03	Wafer Bonding Pressure TF	To have a TF kick off meeting and reconsider the TF name. →Closed

10.2 *New Action Items*

Item #	*Assigned to*	*Details*
3DP&I_20260309-01	SEMI Staff	To send the ballot review results of Doc.#7398 to the ISC A&R SC for procedural review.
3DP&I_20260309-02	5-year review TF (Tsuriya-san)	To Submit SEMI G82 and G95 Line Item Revision Ballot for Cycle 4, 2026.
3DP&I_20260309-03	5-year review TF (Shimamoto-san)	To submit SEMI G74 and G87 Line Item Revision Ballot for Cycle 5, 2026.

11 Next Meeting and Adjournment

The next meeting is scheduled for Friday, June 5, 2026 2:00 PM – 4:00 PM JST via Official Virtual TC Chapter Meeting and at SEMI Japan Office, Tokyo, Japan (Hybrid). See http://www.semi.org/standards-events for the current list of events.

Adjournment: [17:40].

Respectfully submitted by:

Akiko Yoshida

Standards & EHS, SEMI Japan

Phone: +81-3-3222-5863

Email: ayoshida@semi.org

Minutes tentatively approved by:

Kazunori Kato (AiT), Co-chair	March 25, 2026
Masahiro Tsuriya (iNEMI), Co-chair	March 25, 2026
Haruo Shimamoto (AIST), Co-chair	March 30, 2026

Table 14 Index of Available Attachments[#1]

Title	*Title*
01_Required_Meeting_Element Dec 2024_JPupdated	08_SNARF_G95-2603_R1
02_3DP&I_JA_Minutes_20251006_R0	09_SNARF_G074-00-0699-1020R
03_7398_Ballot Review	10_SNARF_G087-00-1108-1020R
04_JRSC Rport_March 2026_R0	11_20260309_SEMI STD Meeting Materials in EN v2_Toshihide Aoshima
05_NA 3DP&I Liaison Report Feb2026 v1	12_TFOF_Sept2024_Toshihide Aoshima（FUJIFILM）v2
06_Staff_HQ Report Feb 2026 _JA_R2	13_20260217_SNARF_Toshihide Aoshima（FUJIFILM）v5
07_SNARF_G82-2603_R1	14_310 Standardization of 2D Codes on Panels

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Akiko Yoshida at the contact information above.